

**LISTING OF THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Previously Presented) An integrated burn-in test method for testing a multi-chip package, comprising:

uploading an integrated burn-in test program to burn-in equipment for testing the multi-chip package having multiple kinds of semiconductor devices; and

conducting a test on each of the semiconductor devices using the integrated burn-in test program.

2. (cancelled)

3. (Previously Presented) The method of claim 1, wherein the multiple kinds of semiconductor devices include one or more of a non-volatile memory, SRAM, and DRAM.

4. (original) The method of claim 1, wherein the multi-chip package performs a memory function.

5. (Previously Presented) The method of claim 1, wherein the test is conducted for each of the semiconductor devices at a different temperature.

6. (Previously Presented) The method of claim 1, wherein the multi-chip package is loaded on a burn-in board and the burn-in board is loaded in a chamber of burn-in equipment.

7. (original) The method of claim 1, wherein the multi-chip package is in the form of a TBGA (thin ball grid array).

8. (Previously Presented) The method of claim 1, wherein the integrated burn-in test program uses a multiplexer selection function for applying a desired test condition during testing of each of the semiconductor devices.

9. (original) The method of claim 1, wherein the integrated burn-in test program has an I/O masking function for blocking some I/O terminals.

10. (Previously Presented) The method of claim 1, wherein the integrated burn-in test program has a function of setting a burn-in temperature condition for each of the semiconductor devices.

11. (Previously Presented) The method of claim 6, wherein after loading the multi-chip package on the burn-in board to the chamber of the burn-in equipment, a contact test is conducted to examine whether an electrical connection of the burn-in board is correct.

12. (original) The method claimed in claim 1, wherein the burn-in test is a monitoring burn-in test.

13. (original) The method of claim 1, wherein the integrated burn-in test program requires only one time bin sorting based on the burn-in test result.

14. (Previously Presented) An integrated burn-in test method for testing a multi-chip package, comprising:

uploading an integrated burn-in test program to test the multi-chip package having multiple kinds of semiconductor devices to burn-in equipment;

conducting a contact test for a burn-in board to examine an electrical connection;

conducting a burn-in test for each of the semiconductor devices using a multiplex selection function of the integrated burn-in test program loaded to the burn-in equipment;

ending the burn-in test; and

bin sorting the multi-chip package based on the burn-in test result.

15. (Previously Presented) The method of claim 14, wherein the burn-in test for each of the semiconductor devices is performed sequentially and the integrated burn-in test program controls the chamber temperature according to a test temperature for each of the semiconductor devices.

16. (Previously Presented) The method of claim 14, wherein each of the semiconductor devices performs a memory function.

17. (original) The method of claim 14, wherein the integrated burn-in test program has an I/O masking function for blocking some I/O terminals.

18. (original) The method of claim 17, wherein each semiconductor device of the multi-chip package has a different number of I/O terminal pins.

19. (original) The method of claim 14, wherein the multi-chip package is in the form of a TBGA (thin ball grid array).

20. (original) The method of claim 14, wherein the burn-in test is a monitoring burn-in test.

21. (Previously Presented) An integrated burn-in test method for testing a multi-chip package, comprising:

providing the multi-chip package formed of multiple kinds of semiconductor devices;  
and

testing the multi-chip package with an integrated burn-in test program, wherein the burn-in test program is adapted to test each of the semiconductor devices.

22. (Previously Presented) The method of claim 21, wherein the testing includes applying a specific test condition during testing of each of the semiconductor devices, wherein the specific test condition is defined by a multiplexer selection function.

23. (original) The method of claim 21, wherein the testing includes blocking some I/O terminals during testing of some semiconductor devices, wherein the blocking is defined by an I/O masking function.

24. (Previously Presented) The method of claim 21, wherein the testing includes setting a specific burn-in temperature condition for each of the semiconductor devices.

25. (Previously Presented) The method of claim 21, wherein the testing includes performing a single contact test.

26. (Previously Presented) The method of claim 21, further comprising:  
a one time bin sorting for the multi-chip package based on the testing result.

27. (Previously Presented) An integrated burn-in test method for testing a multi-chip package, comprising:  
providing the multi-chip package formed of multiple kinds of semiconductor devices;  
testing the multi-chip package with an integrated burn-in test program adapted to test each of the semiconductor devices, including  
performing a single contact test for each of the semiconductor device,  
blocking some I/O terminals during testing of some semiconductor devices,  
wherein the blocking is defined by an I/O masking function,  
setting a specific burn-in temperature condition for each of the semiconductor devices,  
conducting a burn-in test for the multi-chip package by applying a specific test condition for each of the semiconductor devices, wherein the specific test condition is defined by a multiplexer selection function; and  
a one time bin sorting of the multi-chip package based on the testing result.

28. (Previously Presented) The method of claim 1, further comprising:  
loading the multi-chip package to a chamber of the burn-in equipment.
29. (Previously Presented) The method of claim 14, further comprising:  
loading the multi chip-package on the burn-in board; and  
loading the burn-in board into a chamber of the burn-in equipment.